BRIGHTEK

BRIGHTEK (EUROPE) LIMITED

Brighten Up The World With LED !

ISO/TS 16949:2009 BS EN ISO 14001:2004 QC 080000 IECQ HSPM

PRODUCT DATASHEET

ATTENTION
OBSERVE PRECAUTIONS FOR HANDLING ELECTROSTATIC SENSITIVE DEVICES

- ► EMC 2-PIN SMD
- ► 2016 0.52t
- ► Gold White 1800K (PC Amber)

Release Date: 21 November 2022 Version: A1.0

N0W63S08PC

2016 EMC Series

2016 EMC Series

RoHS Compliant

FEATURES:

- **Package:** Top View EMC White Package
- **Forward Current:** 60~150mA
- **Forward Voltage (typ.):** 2.9V
- **Luminous Flux (typ.):** 21lm@60mA
- **Colour:** Gold White (PC Amber)
- **Colour Temperature (CCT):** 1800K
- **Viewing angle:** 120°
- **Materials:**
  - Die: InGaN
  - Resin: Silicon (Yellow Diffused)
  - Package: EMC
- **Operating Temperature:** -40~+85°C
- **Storage Temperature:** -40~+105°C
- **Electrostatics Discharge:** 1000V
- **Grouping parameters:**
  - Forward Voltage
  - Luminous Flux
  - CIE Chromaticity
- **Soldering methods:** Reflow Soldering
- **MSL Level:** 3 according to J-STD020
- **Packing:** 8mm tape with max.5000/reel, ø165mm (6.5'')

APPLICATIONS:

- General Lighting
- Portable Lighting
- Commercial Lighting
- Indoor Lighting
- Backlight for LCD

CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	I_F	150	mA
Pulse Forward Current (Duty 1/10, width≤100μS)	I_{PF}	225	mA
Power Dissipation	P_D	480	mW
Reverse Voltage	V_R	5	V
Reverse Current @10V	I_R	10	μA
Junction Temperature	T_j	120	°C
Electrostatic Discharge	ESD	1000	V
Thermal Resistance (Junction to Solder Point)	R_{THJS}	38	°C/W
Operating Temperature	T_{OPR}	-40~+85	°C
Storage Temperature	T_{STG}	-40~+105	°C
Soldering Temperature	T_{SOL}	230/260 for 10S	°C

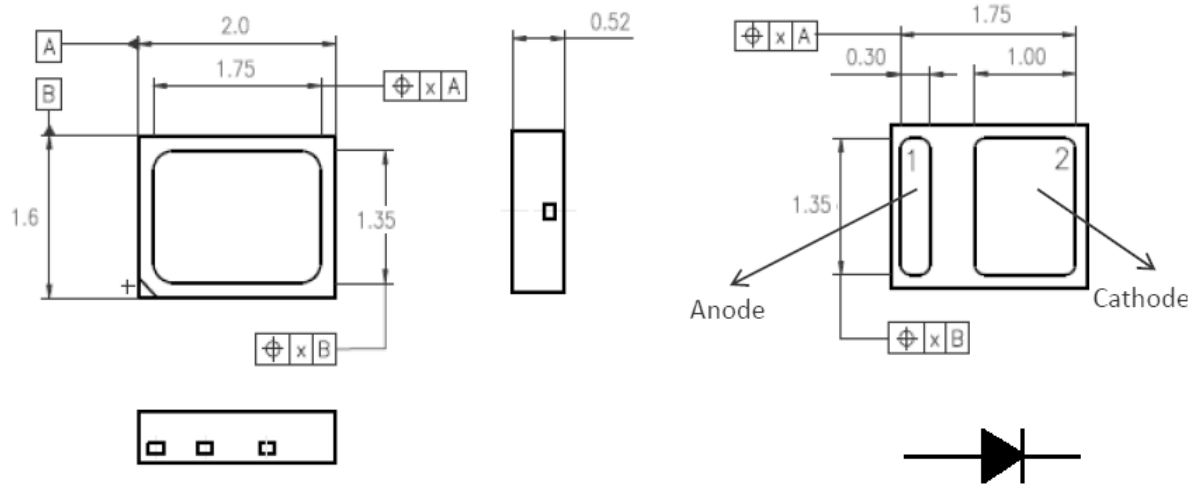
Electrical & Optical Characteristics (Ta=25°C)

Parameter	Symbol	Values			Unit	Test Condition
		Min.	Typ.	Max.		
Forward Voltage	V_F	---	2.9	3.2	V	I_F=60mA
Luminous Flux	Φ_V	18	21	---	lm	I_F=60mA
Chromaticity Coordinates	X	---	0.5725	---	---	I_F=60mA
	Y	---	0.4200	---		
Colour Temperature	CCT	---	1800	---	K	I_F=60mA
Viewing Angle	$2\theta_{1/2}$	---	120	---	deg	I_F=60mA

1. Luminous flux (Φ_V) ±10%, Forward Voltage (V_F) ±0.1V

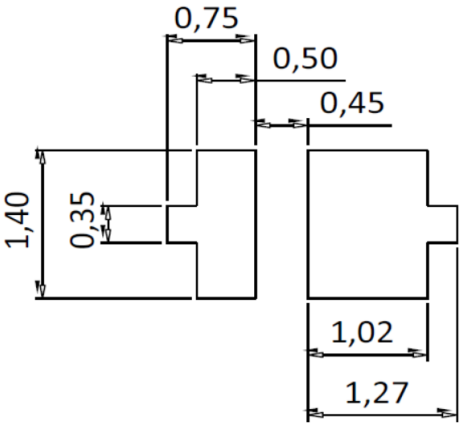
OUTLINE DIMENSION:

Package Dimension:



1. All dimensions are in millimetre (mm).
2. Tolerance ±0.2mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



Recommended PCB Solder Pad

1. Dimensions are in millimetre (mm).
2. Tolerance ±0.1mm with angle tolerance ±0.5°.

BINNING GROUPS:

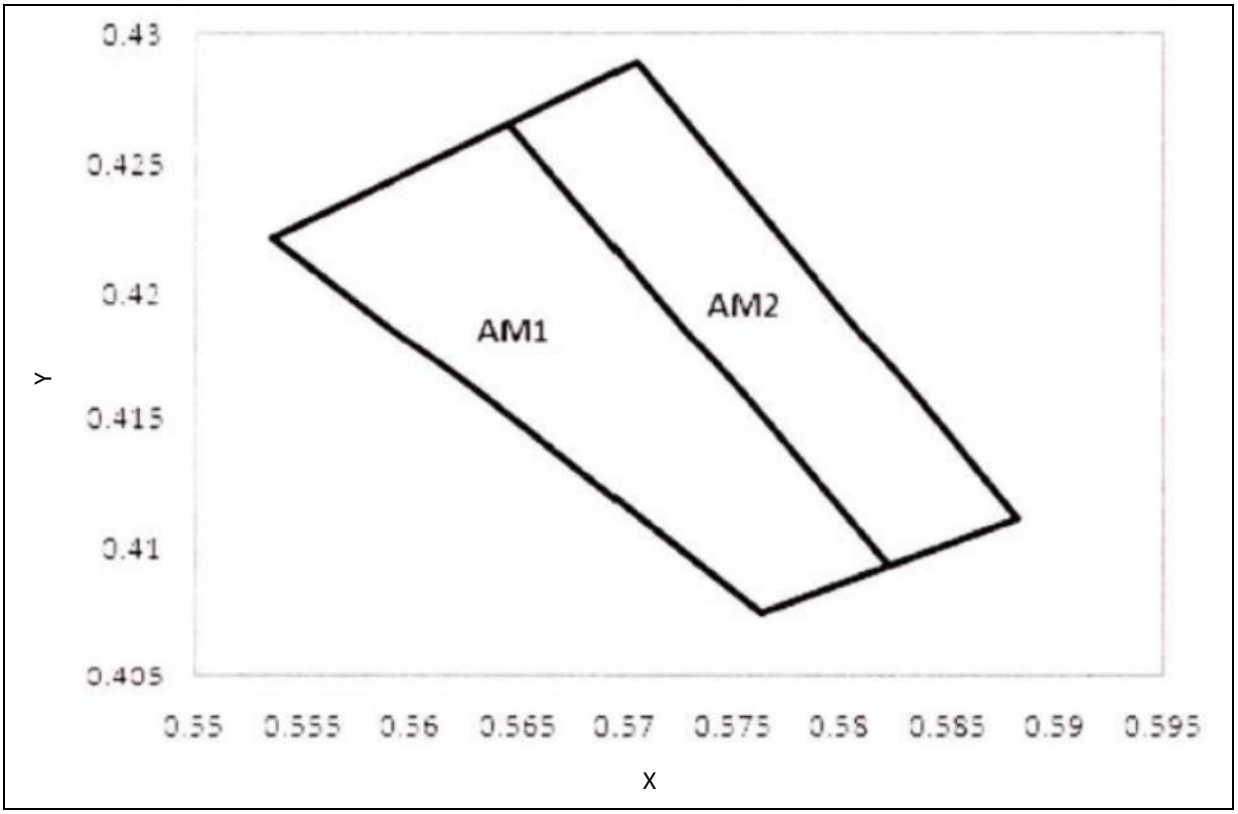
Forward Voltage Classifications (I_F = 60mA):

Code	Min.	Max.	Unit
G3	2.6	2.8	V
H3	2.8	3.0	
J3	3.0	3.2	

Luminous Flux Classifications (I_F = 60mA):

Code	Min.	Max.	Unit
D2	18	20	lm
D3	20	22	
D4	22	24	
D5	24	26	

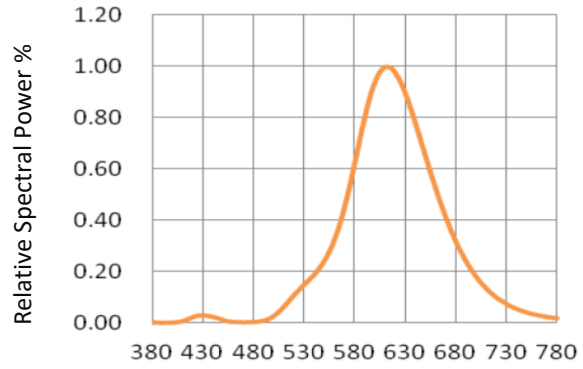
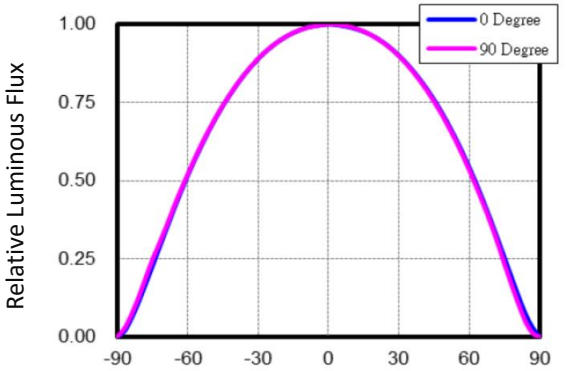
CIE CHROMATICITY DIAGRAM:



Chromaticity Coordinates Classifications (I_F = 60mA):

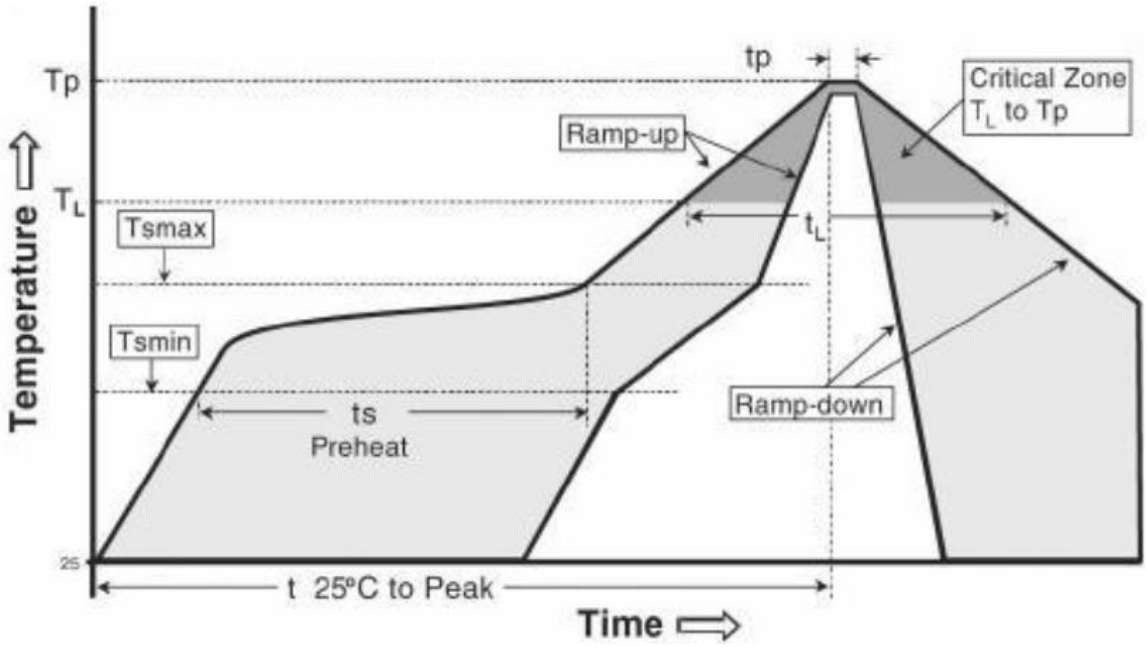
	1		2		3		4	
	X	Y	X	Y	X	Y	X	Y
AM1	0.5764	0.4075	0.5536	0.4221	0.5646	0.4265	0.5824	0.4093
AM2	0.5824	0.4093	0.5646	0.4265	0.5705	0.4289	0.5883	0.4111

ELECTRO-OPTICAL CHARACTERISTICS:

Relative Spectral Power v.s. Wavelength	Directive Radiation
	

RECOMMENDED SOLDERING PROFILE:

Reflow Lead-free Solder:



Temperature Min. (T_{smin})	150°C
Temperature Max. (T_{smax})	200°C
Period from T_{smin} to T_{smax}	60-120 seconds
Ramp-up Rate (T_L to T_P)	Max. 3°C/second
Liquidous Temperature (T_L)	217°C
Time Maintained above T_L	60-150 seconds
Peak Package Temperature (T_P)	Max. 260°C
Time within 5°C of the Specified Classification Temperature T_C	Max. 30 seconds
Ramp-down Rate (T_P to T_L)	Max. 6°C/second
Time from 25°C to Peak Temperature	Max. 8 mins

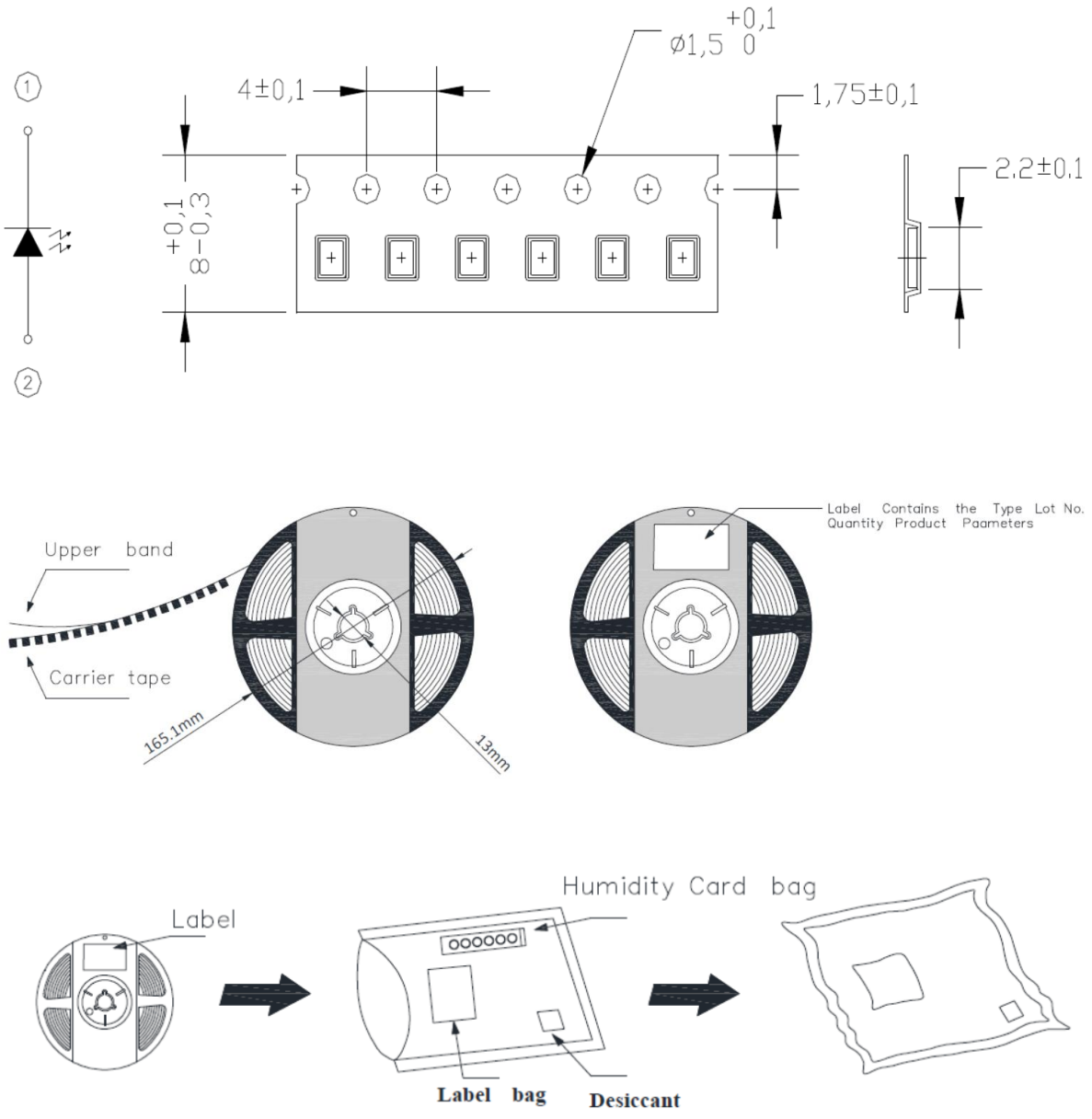
Note:

1. Maximum reflow soldering: 2 times within 24 hours.
2. Before, during, and after soldering, should not apply stress on the components and PCB board.
3. Recommended soldering temperature: 230°C. The maximum soldering temperature should be limited to 260°C for max. 10seconds.

PACKING SPECIFICATION:

Reel Dimension:

Max.5000pcs/reel



PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking before use.

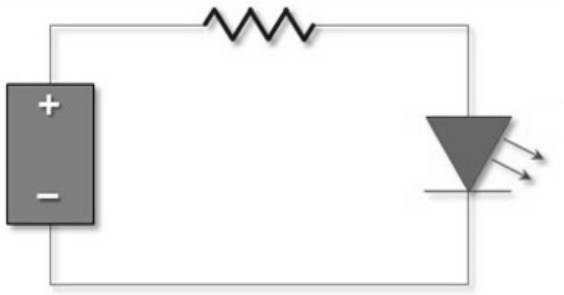
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

- 60±5°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.

REVISION RECORD:

Version	Date	Summary of Revision
A1.0	21/11/2022	Datasheet set-up.